

SOT1376-2

WLCSP4, wafer level chip-scale package; 4 bumps; 0.97 mm x 0.97 mm x 0.54 mm body (backside coating included)

22 August 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP4
Package type industry code	WLCSP4
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	22-8-2017
Manufacturer package code	SOT1376-2

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.94	-	0.97	1	mm
E	package width	0.94	-	0.97	1	mm
A	seated height	0.5	-	0.54	0.58	mm
A ₂	package height	0.285	-	0.31	0.335	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	4	-	



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2. Package outline

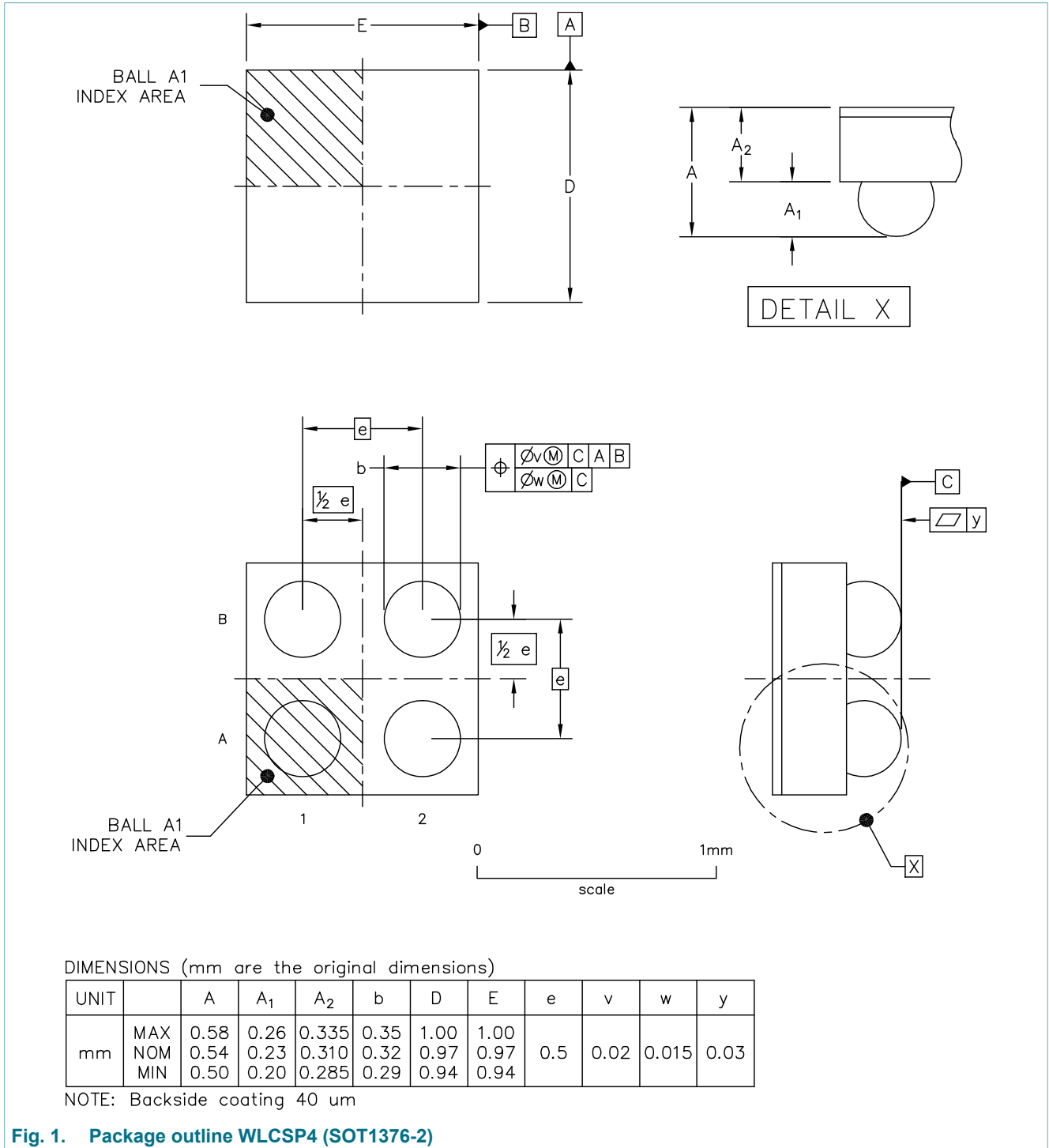


Fig. 1. Package outline WLCSP4 (SOT1376-2)

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3. Legal information

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